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Roberto

Docket No. 55776 (71987)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: C. Huang et al.

U.S. SERIAL NO: 09/823,176

GROUP: 2811

FILED: March 29, 2001

EXAMINER: Gebremariam

FOR: BALL GRID ARRAY SUBSTRATE STRIP WITH WARPAGE-
PREVENTIVE LINKAGE STRUCTURE

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being transmitted by facsimile to Group 2800 of the U.S. Patent & Trademark Office by facsimile number 703-872-9318 on December 20, 2002.

By: 

Steven M. Jensen

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

AMENDMENT

Applicants are in receipt of the Office Action dated September 20, 2002 of the above-referenced application. Please amend the application as follows:

IN THE SPECIFICATION

Please amend the paragraph on page 1, lines 11-16 as follows:

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TECHNOLOGY CENTER 2800

AI BGA (Ball Grid Array) is an advanced type of semiconductor packaging technology which is characterized in the use of a substrate whose front side is used for the mounting of a semiconductor chip thereon, and whose back side is implanted with a grid array of solder balls. During a SMT (Surface Mount Technology) process, the BGA package can be mechanically bonded and electrically coupled to an external printed circuit board (PCB) by means of these solder balls.